MA3D649 (MA6D49)

Silicon planar type (cathode common)

For high-frequency rectification

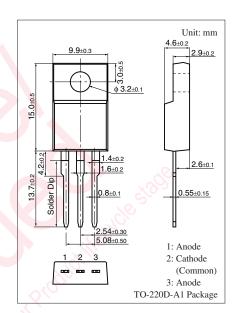
■ Features

- Low forward voltage V_F
- Fast reverse recovery time t_{rr}
- TO-220D (Full-pack package) with high dielectric breakdown voltage
- Easy-to-mount, caused by its V cut lead end

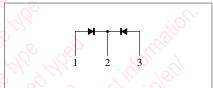
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Repetitive peak reverse voltage	V_{RRM}	200	V	
Non-repetitive peak reverse surge voltage	V _{RSM}	200	V	
Forward current (Average)	I _{F(AV)}	5	A	
Non-repetitive peak forward surge current *	I_{FSM}	30	A	
Junction temperature	T _j	-40 to +150	°C	
Storage temperature	T_{stg}	-40 to +150	°C	

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)





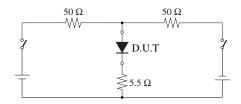


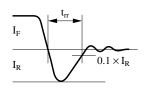
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 2.5 \text{ A}, \ T_C = 25^{\circ}\text{C}$		0	0.98	V
Repetitive peak reverse current	I_{RRM1}	$V_{RRM} = 200 \text{ V}, \ T_{C} = 25^{\circ}\text{C}$	1.90		20	μΑ
	I_{RRM2}	$V_{RRM} = 200 \text{ V}, \ T_j = 150^{\circ}\text{C}$			2	mA
Reverse recovery time *	t _{rr}	$I_F = 1 A, I_R = 1 A$			30	ns
Thermal resistance (j-c)	R _{th(j-c)}	1, 10, 11, 5			3.0	°C/W
Thermal resistance (j-a)	R _{th(j-a)}	is I who			63	°C/W

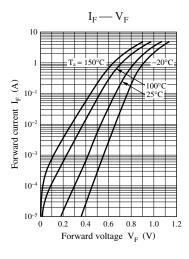
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

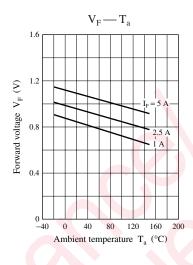
- 2. Absolute frequency of input and output is 10 MHz.
- 3. *: t_{rr} measurement circuit

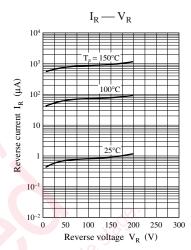


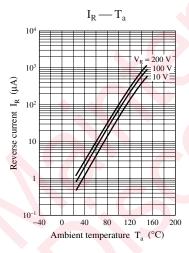


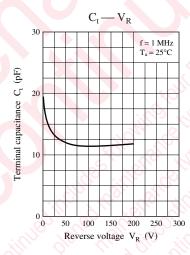
Note) The part number in the parenthesis shows conventional part number.

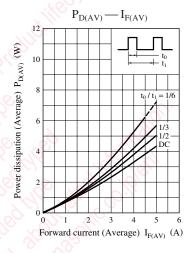


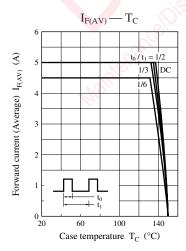












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